

PRODUCT/PROCESS CHANGE NOTIFICATION

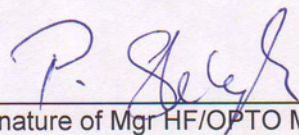
TO: ME-UK: AR  
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DJ, DC, SR, JL, SB, HE

DATE: 06. Nov. 2009  
FROM: MEU Mktg / Eng  
Dr. P. Stelmaszyk  
DEPT.: SEMI

PCN number : PCN-H-05-09

Herewith we want to inform you about the following:

- a) Product change:   
Process change:
- b) Old Mitsubishi type number: All RAxxxx modules  
- except H46M package (handy metal cap)  
- except H58 package (RA01Lxxxx)
- c) New Mitsubishi type number: No change
- d) Expected last order and shipment dates for unchanged devices to be supplied: Not applicable
- e) Expected first shipment date of changed devices: February 2010 starting with production Lot numbers: 09XSA (mass production start Jan. 2010)
- f) Manufacturing location and product line affected: Shimane Masuda Electronics / MEC Semicon
- g) Description of the proposed change: a) change chip plate material (CuMo ⇔ Cu)  
b) change die bond solder (AuSn ⇔ SnAgCuSb)
- h) Comparison table of change attached: Yes  No
- i) Reliability and/or engineering test data are: attached:   
available on request:
- j) Customer spec. / part number: All included

  
(Signature of Mgr HF/OPTO Marketing/ Engineering)

Note: Please comment until 04/12/2009. Otherwise we regard the PCN as accepted.